

Taiwan's UMC, Japan's Elpida team up on 3D technologies

June 21 2010



A picture of a 3D television is seen through 3D glasses displayed at the CommunicAsia 2010 conference and exhibition show in Singapore on June 17. Taiwan's United Microelectronics Corp, the world's number two contract chip maker, and Japan's Elpida Memory said Monday they will develop cutting-edge 3D technologies together.

Taiwan's United Microelectronics Corp, the world's number two contract chip maker, and Japan's Elpida Memory said Monday they will develop cutting-edge 3D technologies together.

Powertech Technology Inc, a Taiwanese company providing testing services, is also joining the project, the three companies said in a statement.

The move comes as electronics firms move to cash in on the popularity of 3D technology, which includes televisions and computers.

The cooperation will focus on technologies that "can massively increase the data transfer rate and reduce [power consumption](#), making possible completely new kinds of high-performance devices", according to the statement.

The three companies did not say how much the project was expected to cost.

(c) 2010 AFP

Citation: Taiwan's UMC, Japan's Elpida team up on 3D technologies (2010, June 21) retrieved 19 April 2024 from <https://phys.org/news/2010-06-taiwan-umc-japan-elpida-team.html>

<p>This document is subject to copyright. Apart from any fair dealing for the purpose of private study or research, no part may be reproduced without the written permission. The content is provided for information purposes only.</p>
--